

### **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

1. (Currently Amended) An ink jet printhead comprising:  
a substrate having a planar support surface;  
a structure supported on the planar support surface, the structure being that is formed by chemical vapor deposition (CVD) to define a planar nozzle plate and depending side walls, the planar nozzle plate being parallel to, and spaced from the planar support surface of the substrate, and the side walls extending between the support surface and the planar nozzle plate;  
a plurality of nozzles incorporated on the structure apertures formed in the planar nozzle plate; and  
at least one respective heater element corresponding to each nozzle aperture for, wherein each heater element is arranged for being in thermal contact with a bubble forming liquid, and  
each heater element is configured to heat at least part of the bubble forming liquid to a temperature above its boiling point to form a gas bubble therein thereby to cause the ejection of a drop of the bubble forming liquid through the nozzle aperture corresponding to that heater element; wherein,  
the at least one heater element is deposited in a plane parallel to both the planar support surface and the planar nozzle plate such that it forms a suspended beam positioned for immersion in the bubble forming liquid so as to be in thermal contact therewith.
2. (Original) The printhead of claim 1 being configured to support the bubble forming liquid in thermal contact with the at least one corresponding heater element, and to support the bubble forming liquid adjacent each nozzle.
3. (Original) The printhead of claim 1 being configured to print on a page and to be a page-width printhead.
4. (Original) The printhead of claim 1 wherein the CVD is of silicon nitride.
5. (Original) The printhead of claim 1 wherein the CVD is of silicon dioxide.

6. (Original) The printhead of claim 1 wherein the CVD is of oxi-nitride.
7. (Cancelled)
8. (Original) The printhead of claim 1 wherein each heater element is configured such that an actuation energy of less than 500 nanojoules (nJ) is required to be applied to that heater element to heat that heater element sufficiently to form a said bubble in the bubble forming liquid thereby to cause the ejection of said drop.
9. (Original) The printhead of claim 1 configured to receive a supply of the bubble forming liquid at an ambient temperature, wherein each heater element is configured such that the energy required to be applied thereto to heat said part of the bubble forming liquid to cause the ejection of said drop is less than the energy required to heat a volume of said ejectable liquid equal to the volume of the said drop, from a temperature equal to said ambient temperature to said boiling point.
10. (Original) The printhead of claim 1 comprising a substrate having a substrate surface, wherein each nozzle has a nozzle aperture opening through the substrate surface, and wherein the areal density of the nozzles relative to the substrate surface exceeds 10,000 nozzles per square cm of substrate surface.
11. (Original) The printhead of claim 1 wherein each heater element has two opposite sides and is configured such that said gas bubble formed by that heater element is formed at both of said sides.
12. (Original) The printhead of claim 1 wherein the bubble which each heater element is configured to form is collapsible and has a point of collapse, and wherein each heater element is configured such that the point of collapse of a bubble formed thereby is spaced from that heater element.
13. (Original) The printhead of claim 1 comprising a structure being less than 10 microns thick, wherein the nozzles are incorporated in the structure.

14. (Original) The printhead of claim 1 comprising a plurality of nozzle chambers each corresponding to a respective nozzle, and a plurality of said heater elements being disposed within each chamber, the heater elements within each chamber being formed on different respective layers.

15. (Original) The printhead of claim 1 wherein each heater element is formed of solid material more than 90% of which, by atomic proportion, is constituted by at least one periodic element having an atomic number below 50.

16. (Original) The printhead of claim 1 wherein each heater element includes solid material and is configured for a mass of less than 10 nanograms of the solid material of that heater element to be heated to a temperature above the boiling point of the bubble forming liquid thereby to heat at least part of the bubble forming liquid to a temperature above said boiling point to cause the ejection of a said drop.

17. (Original) The printhead of claim 1 wherein each heater element is substantially covered by a conformal protective coating, the coating of each heater element having been applied substantially to all sides of the heater element simultaneously such that the coating is seamless.

18. (Currently Amended) A printer system incorporating a printhead, the printhead comprising:

a substrate having a planar support surface;

a structure supported on the planar support surface, the structure being that is formed by chemical vapor deposition (CVD) to define a planar nozzle plate and depending side walls, the planar nozzle plate being parallel to, and spaced from the planar support surface of the substrate, and the side walls extending between the support surface and the planar nozzle plate;

a plurality of nozzle apertures formed in the planar nozzle plate incorporated on the structure; and

at least one respective heater element corresponding to each nozzle aperture for, wherein each heater element is arranged for being in thermal contact with a bubble forming liquid; and

~~each heater element is configured~~ to heat at least part of the bubble forming liquid to a temperature above its boiling point to form a gas bubble therein thereby to cause the ejection of a drop of the bubble forming liquid through the nozzle aperture corresponding to that heater element; wherein,

the at least one heater element is deposited in a plane parallel to both the planar support surface and the planar nozzle plate such that it forms a suspended beam positioned for immersion in the bubble forming liquid so as to be in thermal contact therewith.

19. (Original) The system of claim 18 being configured to support the bubble forming liquid in thermal contact with the at least one corresponding heater element, and to support the bubble forming liquid adjacent each nozzle.
20. (Original) The system of claim 18 being configured to print on a page and to be a page-width printhead.
21. (Original) The system of claim 18 wherein the CVD is of silicon nitride.
22. (Original) The system of claim 18 wherein the CVD is of silicon dioxide.
23. (Original) The system of claim 18 wherein the CVD is of oxi-nitride.
24. (Cancelled)
25. (Original) The system of claim 18 wherein each heater element is configured such that an actuation energy of less than 500 nanojoules (nJ) is required to be applied to that heater element to heat that heater element sufficiently to form a said bubble in the bubble forming liquid thereby to cause the ejection of said drop.
26. (Original) The system of claim 18, wherein the printhead is configured to receive a supply of the bubble forming liquid at an ambient temperature, and wherein each heater element is configured such that the energy required to be applied thereto to heat said part of the bubble forming liquid to cause the ejection of said drop is less than the energy required

to heat a volume of said ejectable liquid equal to the volume of the said drop, from a temperature equal to said ambient temperature to said boiling point.

27. (Original) The system of claim 18 comprising a substrate having a substrate surface, wherein each nozzle has a nozzle aperture opening through the substrate surface, and wherein the areal density of the nozzles relative to the substrate surface exceeds 10,000 nozzles per square cm of substrate surface.

28. (Original) The system of claim 18 wherein each heater element has two opposite sides and is configured such that said gas bubble formed by that heater element is formed at both of said sides.

29. (Original) The system of claim 18 wherein the bubble which each heater element is configured to form is collapsible and has a point of collapse, and wherein each heater element is configured such that the point of collapse of a bubble formed thereby is spaced from that heater element.

30. (Original) The system of claim 18 comprising a structure being less than 10 microns thick, wherein the nozzles are incorporated in the structure.

31. (Original) The system of claim 18 comprising a plurality of nozzle chambers each corresponding to a respective nozzle, and a plurality of said heater elements being disposed within each chamber, the heater elements within each chamber being formed on different respective layers.

32. (Original) The system of claim 18 wherein each heater element is formed of solid material more than 90% of which, by atomic proportion, is constituted by at least one periodic element having an atomic number below 50.

33. (Original) The system of claim 18 wherein each heater element includes solid material and is configured for a mass of less than 10 nanograms of the solid material of that heater element to be heated to a temperature above the boiling point of the bubble forming liquid thereby to heat at least part of the bubble forming liquid to a temperature above said boiling point to cause the ejection of a said drop.

34. The system of claim 18 wherein each heater element is substantially covered by a conformal protective coating, the coating of each heater element having been applied substantially to all sides of the heater element simultaneously such that the coating is seamless.

35. (Currently Amended) A method of ejecting a drop of an ejectable liquid from a printhead that has:

a substrate having a planar support surface;

a structure supported on the planar support surface, the structure being formed by chemical vapor deposition (CVD) to define a planar nozzle plate and depending side walls, the planar nozzle plate being parallel to, and spaced from the planar support surface of the substrate, and the side walls extending between the support surface and the planar nozzle plate;

a plurality of nozzle apertures formed in the planar nozzle plate; and  
at least one respective heater element corresponding to each nozzle aperture for thermal contact with a bubble forming liquid to heat at least part of the bubble forming liquid to a temperature above its boiling point to form a gas bubble therein thereby to cause the ejection of a drop of the bubble forming liquid through the nozzle aperture corresponding to that heater element; wherein,

the at least one heater element is deposited in a plane parallel to both the planar support surface and the planar nozzle plate such that it forms a suspended beam positioned for immersion in the bubble forming liquid so as to be in thermal contact therewith, the printhead comprising a plurality of nozzles and at least one respective heater element corresponding to each nozzle, the method comprising the steps of:

feeding bubble forming liquid to immerse each of the heater elements and feeding ejectable liquid to the nozzle plate to be retained adjacent the nozzle apertures; providing the printhead, including forming a structure by chemical vapor deposition (CVD), which structure defines nozzle apertures each forming part of a respective nozzle;-----

heating at least one heater element corresponding to a ~~nozzle~~ nozzle aperture so as to heat at least part of a bubble forming liquid which is in thermal contact with the at least one heated heater element to a temperature above the boiling point of the bubble forming liquid; generating a gas bubble in the bubble forming liquid by said step of heating; and

causing the drop of the bubble forming liquid to be ejected through the nozzle aperture corresponding to the at least one heated heater element by said step of generating a gas bubble.

36. (Original) The method of claim 35 comprising, before said step of heating, the steps of:

disposing the bubble forming liquid in thermal contact with the heater elements.

37. (Original) The method of claim 35 wherein the step of providing the printhead comprises forming the structure by CVD of silicon nitride.

38. (Original) The method of claim 35 wherein the step of providing the printhead comprises forming the structure by CVD of silicon dioxide.

39. (Original) The method of claim 35 wherein the step of providing the printhead comprises forming the structure by CVD of oxi-nitride.

40. (Cancelled)

41. (Original) The method of claim 35 wherein the step of heating a heating element having at least one heater element is effected by applying an actuation energy of less than 500nJ to each heater element to be heated.

42. (Original) The method of claim 35, comprising, prior to the step of heating at least one heater element, the step of receiving a supply of the bubble forming liquid, at an ambient temperature, to the printhead, wherein the step of heating is effected by applying heat energy to each such heater element, wherein said applied heat energy is less than the energy required to heat a volume of said bubble forming liquid equal to the volume of said drop, from a temperature equal to said ambient temperature to said boiling point.

43. (Original) The method of claim 35 wherein, in the step of providing the printhead, the printhead includes a substrate having a substrate surface, and each nozzle has a nozzle aperture opening through the substrate surface wherein the areal density of the nozzles relative to the substrate surface exceeds 10,000 nozzles per square cm of substrate surface.

44. (Original) The method of claim 35 wherein each heater element has two opposite sides and wherein, in the step of generating gas bubble, the bubble is generated at both of said sides of each heated heater element.

45. (Original) The method of claim 35 wherein, in the step of generating gas bubble, the generated bubble is collapsible and has a point of collapse, and is generated such that the point of collapse is spaced from the at least one heated heater element.

46. (Original) The method of claim 35 wherein, in the step of providing the printhead, the printhead has a structure which is less than 10 microns thick and which incorporates said nozzles.

47. (Original) The method of claim 35 wherein the printhead has a plurality of nozzle chambers each chamber corresponding to a respective nozzle and wherein the step of providing the printhead includes forming a plurality of heater elements in each chamber, such that the heater elements in each chamber are formed on different respective layers to one another.

48. (Original) The method of claim 35 wherein, in the step of providing the printhead, each heater element is formed of solid material more than 90% of which, by atomic proportion, is constituted by at least one periodic element having an atomic number below 50.

49. (Original) The method of claim 35 wherein each heater element includes solid material and wherein the step of heating at least one heater element includes heating a mass of less than 10 nanograms of the solid material of each such heater element to a temperature above the boiling point of the bubble forming liquid.